

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3063519

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the NAME OF INVENTOR previously recorded on Reel 030697 Frame 0842. Assignor(s) hereby confirms the THE INVENTOR'S NAME SHOULD BE VENKATA GIRISH VADLAMUDI.
CONVEYING PARTY DATA	
Name	Execution Date
DEBESH KUMAR SAHU	08/13/2014
VENKATA GIRISH VADLAMUDI	08/13/2014
VENKATA SIVA PRASAD RAO GUDE	10/08/2014
VENKATA APPALA NAIDU BABBADI	08/13/2014
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13928609
CORRESPONDENCE DATA	
Fax Number:	(703)391-2901
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7033912900
Email:	ptonoticesqc@marburylaw.com
Correspondent Name:	THE MARBURY LAW GROUP, PLLC
Address Line 1:	11800 SUNRISE VALLEY DRIVE
Address Line 2:	15TH FLOOR
Address Line 4:	RESTON, VIRGINIA 20191
ATTORNEY DOCKET NUMBER:	130721 / 1376-1250
NAME OF SUBMITTER:	ROBERT M. HANSEN
SIGNATURE:	/Robert M. Hansen/
DATE SIGNED:	10/14/2014
Total Attachments: 9	
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UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

JUNE 28, 2013

PTAS

THE MARBURY LAW GROUP, PLLC
11800 SUNRISE VALLEY DRIVE
15TH FLOOR
RESTON, VA 20191

502400458

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT RECORDATION BRANCH OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE ASSIGNMENT RECORDATION BRANCH AT 571-272-3350. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, MAIL STOP: ASSIGNMENT RECORDATION BRANCH, P.O. BOX 1450, ALEXANDRIA, VA 22313.

RECORDATION DATE: 06/27/2013

REEL/FRAME: 030697/0842
NUMBER OF PAGES: 5

BRIEF: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

DOCKET NUMBER: 130721 / 1376-1250

ASSIGNOR:

GUDE, VENKATA SIVA PRASAD RAO

DOC DATE: 06/07/2013

ASSIGNOR:

SAHU, DEBESH KUMAR

DOC DATE: 06/07/2013

ASSIGNOR:

BABBADI, VENKATA APPALA NAIDU

DOC DATE: 06/07/2013

ASSIGNOR:

~~GIRISH, VADLAMUDI VENKATA~~
Venkata Girish Vadlamudi

DOC DATE: 06/07/2013

ASSIGNEE:

QUALCOMM INCORPORATED
5775 MOREHOUSE DRIVE
SAN DIEGO, CALIFORNIA 92121-1714

APPLICATION NUMBER: 13928609

FILING DATE:

PATENT NUMBER:

ISSUE DATE:

TITLE: FAST ACQUISITION IN MULTI-SUBSCRIBER IDENTITY MODULE (SIM)
DEVICES

ASSIGNMENT RECORDATION BRANCH
PUBLIC RECORDS DIVISION

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Venkata Siva Prasad Rao GUDE</td> <td>06/07/2013</td> </tr> <tr> <td>Debesh Kumar SAHU</td> <td>06/07/2013</td> </tr> <tr> <td>Venkata Appala Naidu BABBADI</td> <td>06/07/2013</td> </tr> <tr> <td>Vadlamudi Venkata GIRISH- Venkata Giren Vadlamudi</td> <td>06/07/2013</td> </tr> </tbody> </table>		Name	Execution Date	Venkata Siva Prasad Rao GUDE	06/07/2013	Debesh Kumar SAHU	06/07/2013	Venkata Appala Naidu BABBADI	06/07/2013	Vadlamudi Venkata GIRISH- Venkata Giren Vadlamudi	06/07/2013
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<table border="1"> <tr> <td>Name:</td> <td>QUALCOMM Incorporated</td> </tr> <tr> <td>Street Address:</td> <td>5775 Morehouse Drive</td> </tr> <tr> <td>City:</td> <td>San Diego</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121-1714</td> </tr> </table>		Name:	QUALCOMM Incorporated	Street Address:	5775 Morehouse Drive	City:	San Diego	State/Country:	CALIFORNIA	Postal Code:	92121-1714
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CORRESPONDENCE DATA											
Fax Number: 7033912901 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 7033912900 Email: ptonotices@marburylaw.com Correspondent Name: The Marbury Law Group, PLLC Address Line 1: 11800 Sunrise Valley Drive Address Line 2: 15th Floor Address Line 4: Reston, VIRGINIA 20191											
ATTORNEY DOCKET NUMBER:	130721 / 1376-1250										
NAME OF SUBMITTER:	Robert M. Hansen										
Signature:	/Robert M. Hansen/										

OP \$40.00 13928609

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India;
2. **Venkata Girish VADLAMUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India;
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India; and
4. **Venkata Appala Naidu BABBADI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to FAST ACQUISITION IN MULTI-SUBSCRIBER IDENTITY MODULE (SIM) DEVICES (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/928,609 filed June 27, 2013, Qualcomm Reference No. 130721, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Ay, INDIA, on 13-08-2014 Debesh K. Sahu
LOCATION DATE Debesh Kumar SAHU

Done at Hyderabad, on 13-08-2014 Girish Vadamudi
LOCATION DATE Venkata Girish VADLAMUDI

Done at _____, on _____
LOCATION DATE Venkata Siva Prasad Rao GUDE

Done at Hyderabad, on 13-08-2014 Appala Naidu
LOCATION DATE Venkata Appala Naidu BABBADI

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India;
2. **Venkata Girish VADLAMUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1747, and a resident of Hyderabad, India;
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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE **Debesh Kumar SAHU**

Done at _____, on _____
LOCATION DATE **Venkata Girish VADLAMUDI**

Done at SAN DIEGO, CA, on 10/8/14
LOCATION DATE **Venkata Siva Prasad Rao GUDE**

Done at _____, on _____
LOCATION DATE **Venkata Appala Naidu BABBADI**